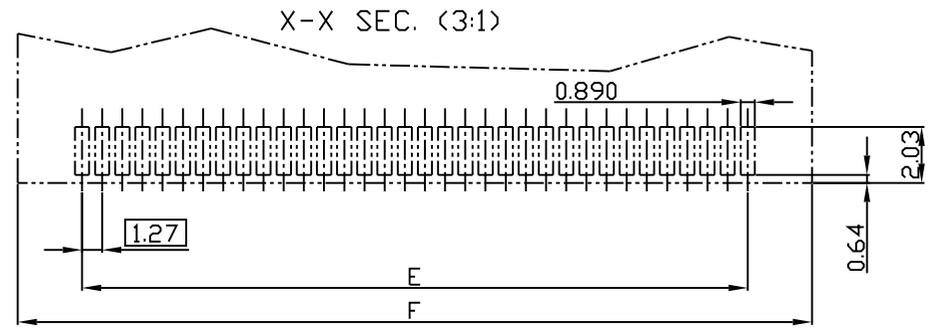
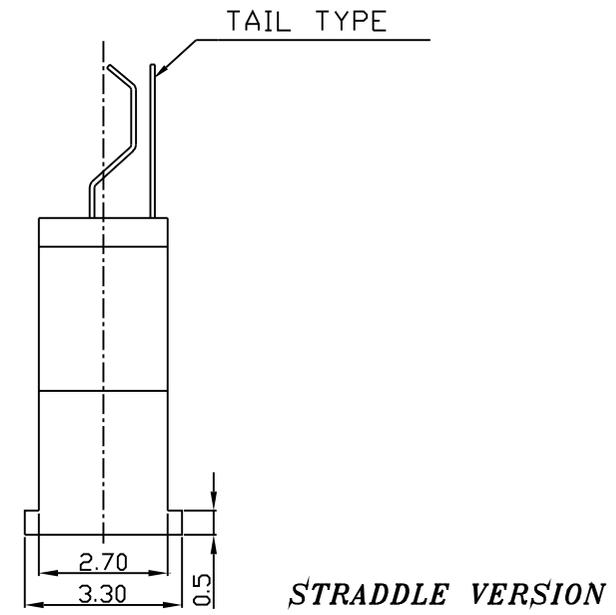
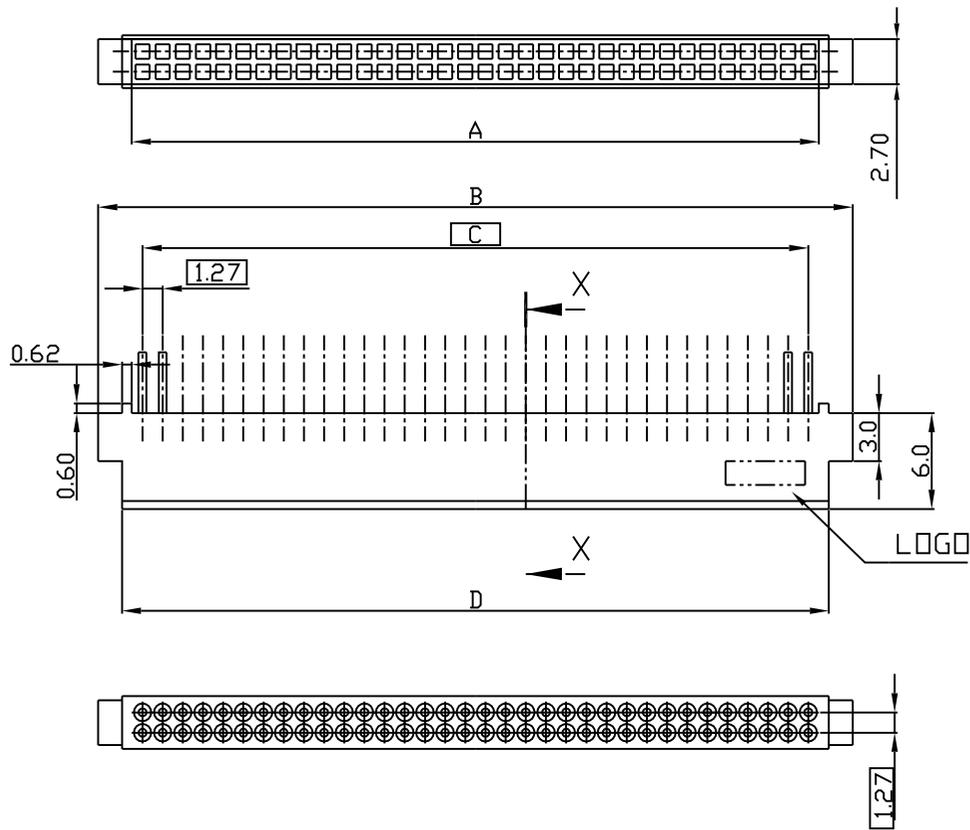


1 2 3 4 5 6 7 8 9 0

J  
I  
H  
G  
F  
E  
D  
C  
B  
A



APPLICABLE CARD THICKNESS 0.3mm to 0.5mm

CKT	PART NO.	A	B	C	D	E	F
50	CFC-SExxx-50	31.80	35.82	30.48	33.02	30.48	37.60



PART NO. CFC-SExxx-50

DWG NO. CFC-SExxx-50

FILE NO.

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION

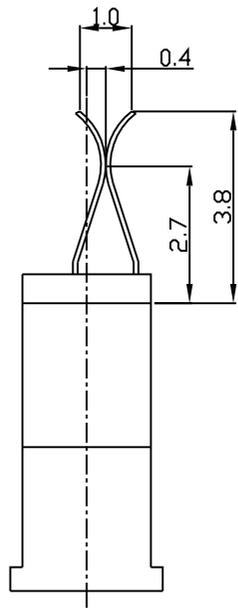
TOLERANCES ARE

.X ± 0.2  
.XX ± 0.1  
.XXX ±  
AWG

DESCRIPTION: **IC MEMORY CARD**

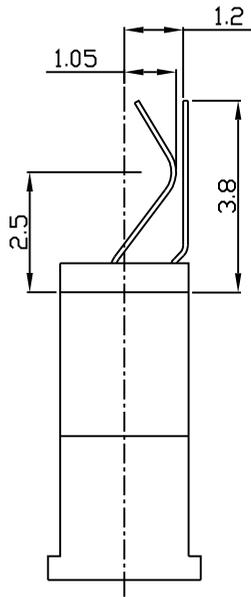
AREA	REVISIONS	HK	DATE
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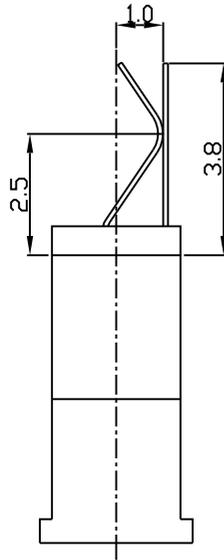
TYPE 1

0.4 OFFSET



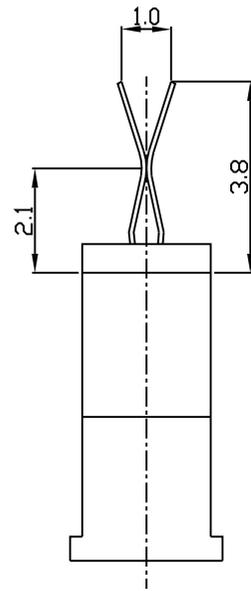
TYPE 2

1.05 OFFSET



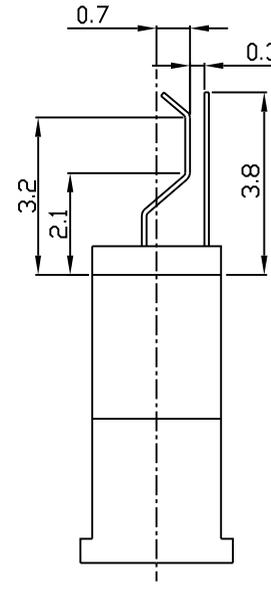
TYPE 3

1.0 OFFSET



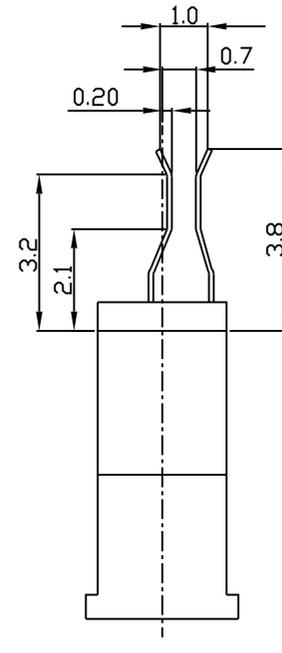
TYPE 4

0 OFFSET



TYPE 5

0.7 OFFSET



TYPE 6

0.2 OFFSET

TAIL TYPE



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PART NO. CFC-SExxx-50

DWG NO. CFC-SExxx-50

FILE NO.

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION



TOLERANCES ARE

.X ± 0.2

.XX ± 0.1

.XXX ±

AWG

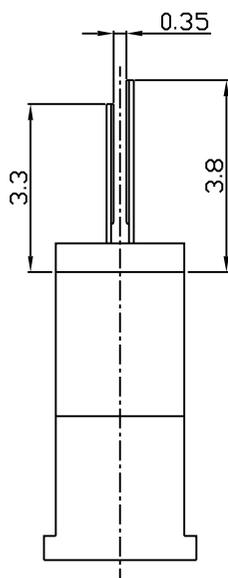
DESCRIPTION:

AREA

REVISIONS

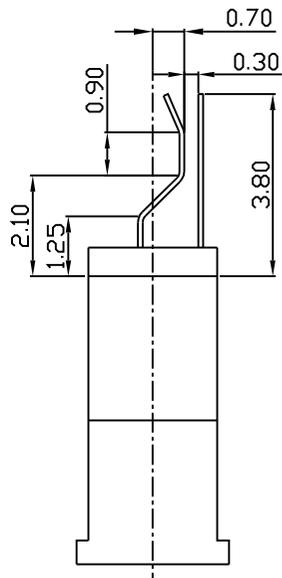
HK

DATE



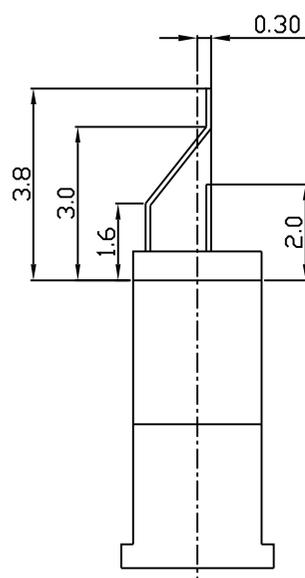
TYPE 7

0 OFFSET



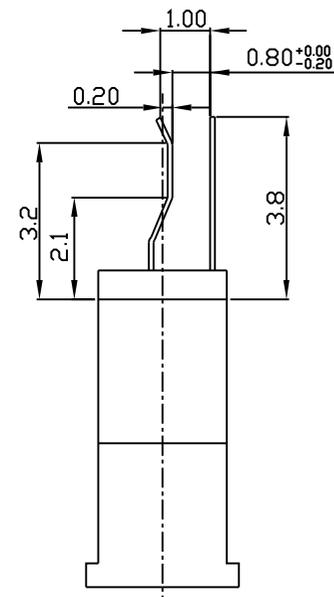
TYPE 8

0.7 OFFSET



TYPE 9

0.3 OFFSET



TYPE A

0.2 OFFSET

NOTE:

1.MATERIAL:HOUSING-LCP (UL94V-0) 30% G.F. FILLED  
COLOR:BLACK

TERMINAL:BERYLLIUM COPPER t=0.1mm

2.PLATING:CONTACT-GOLD (SEE NOTE4 OPTION)  
TAIL-100u"MIN Sn/Pb 90/10  
BOTH OVER 50u"MIN Ni.

3.THE SOLDER PAD DIMENSION IS RECOMMENDED  
FOR IR SOLDERING PROCESS. IF NOT IR

SOLDERING PROCESS, THE DIMENSION COULD BE ADJUSTED.

4.CONTACT RETENTION FORCE:700g MIN..INSERTING FORCE:4kg MAX..

TAIL TYPE

CFC-SExxx-50-LF

LEADFREE

- SE040:TYPE 1
- SE101:TYPE 2
- SE100:TYPE 3
- SE000:TYPE 4
- SE070:TYPE 5
- SE025:TYPE 6
- SE003:TYPE 7
- SE073:TYPE 8
- SW03:TYPE 9
- SE028:TYPE A

RoHS Compliant



PART NO. CFC-SExxx-50

DWG NO. CFC-SExxx-50

FILE NO.

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION



TOLERANCES ARE

.X ± 0.2  
.XX ± 0.1  
.XXX ±  
AWG

DESCRIPTION:

AREA

REVISIONS

HK

DATE

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